

## FEATURES

- **Sample Rate: 25Mpsps**
- **-40°C to 125°C Operation**
- **Single 3V Supply (2.8V to 3.5V)**
- **Low Power: 75mW**
- **71.4dB SNR**
- **90dB SFDR**
- **No Missing Codes**
- **Flexible Input: 1V<sub>P-P</sub> to 2V<sub>P-P</sub> Range**
- **575MHz Full Power Bandwidth S/H**
- **Clock Duty Cycle Stabilizer**
- **Shutdown and Nap Modes**
- **Pin Compatible Family**
- **LTC2246H (14-Bit), LTC2226H (12-Bit)**
- **48-Pin (7mm × 7mm) LQFP Package**

## APPLICATIONS

- Automotive
- Industrial
- Wireless and Wired Broadband Communication

## DESCRIPTION

The LTC<sup>®</sup>2226H is a 12-bit 25Mpsps, low power 3V A/D converter designed for digitizing high frequency, wide dynamic range signals. The LTC2226H is perfect for demanding imaging and communications applications with AC performance that includes 71.4dB SNR and 90dB SFDR.

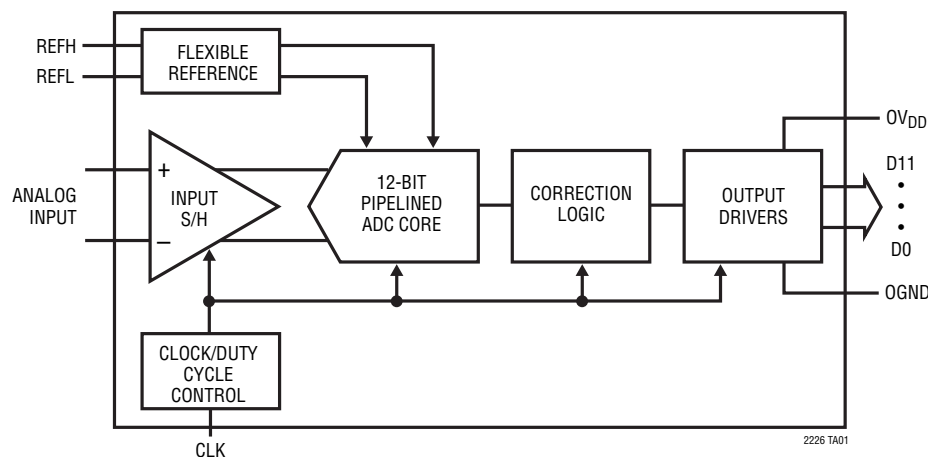
DC specs include  $\pm 0.3\text{LSB}$  INL (typ),  $\pm 0.3\text{LSB}$  DNL (typ) and no missing codes over temperature. The transition noise is a low  $0.25\text{LSB}_{\text{RMS}}$ .

A single 3V supply allows low power operation. A separate output supply allows the outputs to drive 0.5V to 3.6V logic.

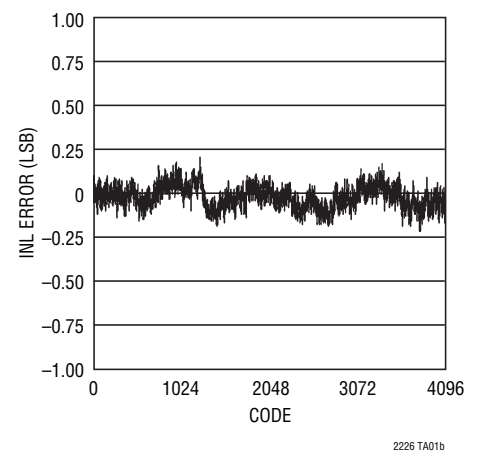
A single-ended CLK input controls converter operation. An optional clock duty cycle stabilizer allows high performance at full speed for a wide range of clock duty cycles.

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## TYPICAL APPLICATION



**Typical INL, 2V Range**



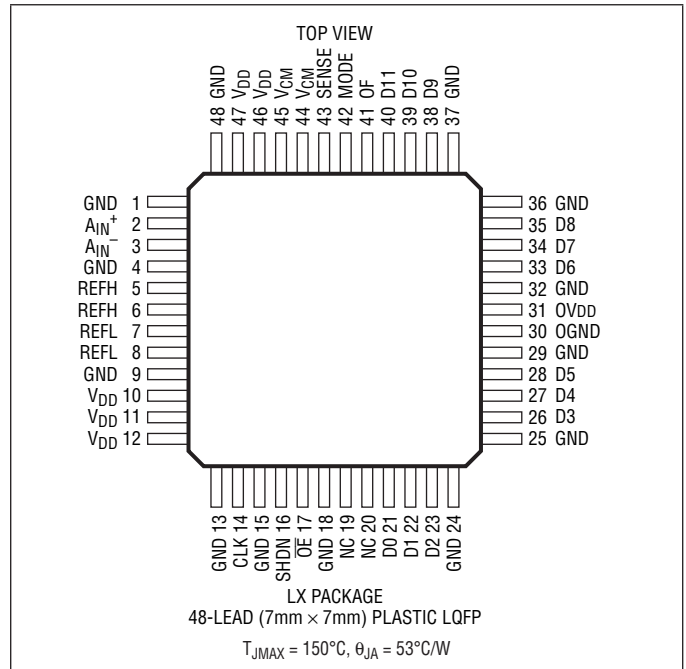
# LTC2226H

## ABSOLUTE MAXIMUM RATINGS

$OV_{DD} = V_{DD}$  (Notes 1, 2)

Supply Voltage ( $V_{DD}$ )	4V
Digital Output Ground Voltage (OGND)	-0.3V to 1V
Analog Input Voltage (Note 3)	-0.3V to ( $V_{DD} + 0.3V$ )
Digital Input Voltage	-0.3V to ( $V_{DD} + 0.3V$ )
Digital Output Voltage	-0.3V to ( $OV_{DD} + 0.3V$ )
Power Dissipation	1500mW
Operating Temperature Range	-40°C to 125°C
Storage Temperature Range	-65°C to 150°C

## PIN CONFIGURATION



## ORDER INFORMATION

LEAD FREE FINISH	PART MARKING	PACKAGE DESCRIPTION	TEMPERATURE RANGE
LTC2226HLX#PBF	LTC2226LX	48-Lead (7mm × 7mm) Plastic LQFP	-40°C to 125°C
LEAD BASED FINISH	PART MARKING	PACKAGE DESCRIPTION	TEMPERATURE RANGE
LTC2226HLX	LTC2226LX	48-Lead (7mm × 7mm) Plastic LQFP	-40°C to 125°C

Consult LTC Marketing for parts specified with wider operating temperature ranges.

For more information on lead free part marking, go to: <http://www.linear.com/leadfree/>

For more information on tape and reel specifications, go to: <http://www.linear.com/tapeandree/>

## CONVERTER CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ . (Note 4)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
Resolution (No Missing Codes)		●	12		Bits	
Integral Linearity Error	Differential Analog Input (Note 5)	●	-1.5	±0.3	1.5	LSB
Differential Linearity Error	Differential Analog Input	●	-0.8	±0.15	0.8	LSB
Offset Error	(Note 6)	●	-15	±2	15	mV
Gain Error	External Reference	●	-3	±0.5	3	%FS
Offset Drift			±10		μV/°C	
Full-Scale Drift	Internal Reference		±30		ppm/°C	
	External Reference		±5		ppm/°C	
Transition Noise	SENSE = 1V		0.25		LSB <sub>RMS</sub>	

2226hfc

## ANALOG INPUT

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ . (Note 4)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$V_{IN}$	Analog Input Range ( $A_{IN}^+ - A_{IN}^-$ )	$2.8V < V_{DD} < 3.5V$ (Note 7)	●	$\pm 0.5V$ to $\pm 1V$		V
$V_{IN, CM}$	Analog Input Common Mode ( $A_{IN}^+ + A_{IN}^-$ )/2	Differential Input (Note 7) Single Ended Input (Note 7)	● ●	1 1.5	1.9 2	V V
$I_{IN}$	Analog Input Leakage Current	$0V < A_{IN}^+, A_{IN}^- < V_{DD}$	●	-10	10	$\mu\text{A}$
$I_{SENSE}$	SENSE Input Leakage	$0V < SENSE < 1V$	●	-10	10	$\mu\text{A}$
$I_{MODE}$	MODE Pin Leakage		●	-10	10	$\mu\text{A}$
$t_{AP}$	Sample-and-Hold Acquisition Delay Time			0		ns
$t_{JITTER}$	Sample-and-Hold Acquisition Delay Time Jitter			0.2		$\text{pSRMS}$
CMRR	Analog Input Common Mode Rejection Ratio			80		dB

## DYNAMIC ACCURACY

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ .  $A_{IN} = -1\text{dBFS}$ . (Note 4)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
SNR	Signal-to-Noise Ratio	5MHz Input 12.5MHz Input 70MHz Input	●	69.6 71.4 71.2 70.9		dB dB dB
SFDR	Spurious Free Dynamic Range 2nd or 3rd Harmonic	5MHz Input 12.5MHz Input 70MHz Input	●	74 90 90 85		dB dB dB
SFDR	Spurious Free Dynamic Range 4th Harmonic or Higher	5MHz Input 12.5MHz Input 70MHz Input	●	78 90 90 90		dB dB dB
S/(N+D)	Signal-to-Noise Plus Distortion Ratio	5MHz Input 12.5MHz Input 70MHz Input	●	69.1 71.4 71.2 70.8		dB dB dB
IMD	Intermodulation Distortion	$f_{IN1} = 4.3\text{MHz}$ , $f_{IN2} = 4.6\text{MHz}$		90		dB

## INTERNAL REFERENCE CHARACTERISTICS

$T_A = 25^\circ\text{C}$ . (Note 4)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$V_{CM}$ Output Voltage	$I_{OUT} = 0$	1.475	1.500	1.525	V
$V_{CM}$ Output Tempco			$\pm 25$		ppm/ $^\circ\text{C}$
$V_{CM}$ Line Regulation	$2.8V < V_{DD} < 3.5V$		3		mV/V
$V_{CM}$ Output Regulation	$-1\text{mA} < I_{OUT} < 1\text{mA}$		4		$\Omega$

## DIGITAL INPUTS AND DIGITAL OUTPUTS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ . (Note 4)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
<b>LOGIC INPUTS (CLK, <math>\overline{OE}</math>, SHDN)</b>						
$V_{IH}$	High Level Input Voltage	$V_{DD} = 3V$	●	2		V
$V_{IL}$	Low Level Input Voltage	$V_{DD} = 3V$	●		0.8	V
$I_{IN}$	Input Current	$V_{IN} = 0V$ to $V_{DD}$	●	-10	10	$\mu\text{A}$
$C_{IN}$	Input Capacitance	(Note 7)		3		pF

## DIGITAL INPUTS AND DIGITAL OUTPUTS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ . (Note 4)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
<b>LOGIC OUTPUTS</b>						
<b><math>OV_{DD} = 3V</math></b>						
$C_{OZ}$	Hi-Z Output Capacitance	$\overline{OE} = \text{High}$ (Note 7)		3		pF
$I_{SOURCE}$	Output Source Current	$V_{OUT} = 0V$		50		mA
$I_{SINK}$	Output Sink Current	$V_{OUT} = 3V$		50		mA
$V_{OH}$	High Level Output Voltage	$I_O = -10\mu\text{A}$ $I_O = -200\mu\text{A}$	● 2.7	2.995 2.99		V V
$V_{OL}$	Low Level Output Voltage	$I_O = 10\mu\text{A}$ $I_O = 1.6\text{mA}$	●	0.005 0.09	0.4	V V
<b><math>OV_{DD} = 2.5V</math></b>						
$V_{OH}$	High Level Output Voltage	$I_O = -200\mu\text{A}$		2.49		V
$V_{OL}$	Low Level Output Voltage	$I_O = 1.6\text{mA}$		0.09		V
<b><math>OV_{DD} = 1.8V</math></b>						
$V_{OH}$	High Level Output Voltage	$I_O = -200\mu\text{A}$		1.79		V
$V_{OL}$	Low Level Output Voltage	$I_O = 1.6\text{mA}$		0.09		V

## POWER REQUIREMENTS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ . (Note 8)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$V_{DD}$	Analog Supply Voltage	(Note 9)	● 2.8	3	3.5	V
$OV_{DD}$	Output Supply Voltage	(Note 9)	● 0.5	3	3.6	V
$I_{VDD}$	Supply Current			25	30	mA
$P_{DISS}$	Power Dissipation			75	90	mW
$P_{SHDN}$	Shutdown Power	SHDN = H, $\overline{OE} = \text{H}$ , No CLK		2		mW
$P_{NAP}$	Nap Mode Power	SHDN = H, $\overline{OE} = \text{L}$ , No CLK		15		mW

## TIMING CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ . (Note 4)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$f_S$	Sampling Frequency	(Note 9)	● 1		25	MHz
$t_L$	CLK Low Time	Duty Cycle Stabilizer Off Duty Cycle Stabilizer On (Note 7)	● 18.9 ● 5	20 20	500 500	ns ns
$t_H$	CLK High Time	Duty Cycle Stabilizer Off Duty Cycle Stabilizer On (Note 7)	● 18.9 ● 5	20 20	500 500	ns ns
$t_{AP}$	Sample-and-Hold Aperture Delay			0		ns
$t_D$	CLK to DATA Delay	$C_L = 5\text{pF}$ (Note 7)	● 1.4	2.7	6	ns
	Data Access Time After $\overline{OE}\downarrow$	$C_L = 5\text{pF}$ (Note 7)	●	4.3	12	ns
	BUS Relinquish Time	(Note 7)	●	3.3	10	ns
	Pipeline Latency			5		Cycles

## ELECTRICAL CHARACTERISTICS

**Note 1:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

**Note 2:** All voltage values are with respect to ground with GND and OGND wired together (unless otherwise noted).

**Note 3:** When these pin voltages are taken below GND or above  $V_{DD}$ , they will be clamped by internal diodes. This product can handle input currents of greater than 100mA below GND or above  $V_{DD}$  without latchup.

**Note 4:**  $V_{DD} = 3V$ ,  $f_{SAMPLE} = 25MHz$ , input range =  $2V_{P-P}$  with differential drive, unless otherwise noted.

**Note 5:** Integral nonlinearity is defined as the deviation of a code from a straight line passing through the actual endpoints of the transfer curve. The deviation is measured from the center of the quantization band.

**Note 6:** Offset error is the offset voltage measured from  $-0.5$  LSB when the output code flickers between 0000 0000 0000 and 1111 1111 1111.

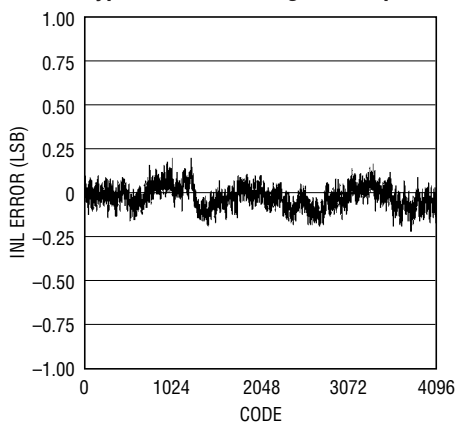
**Note 7:** Guaranteed by design, not subject to test.

**Note 8:**  $V_{DD} = 3V$ ,  $f_{SAMPLE} = 25MHz$ , input range =  $1V_{P-P}$  with differential drive.

**Note 9:** Recommended operating conditions.

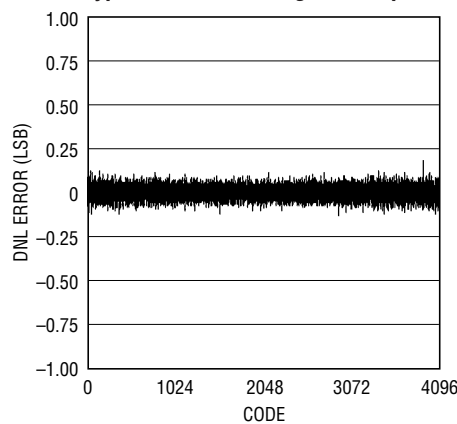
## TYPICAL PERFORMANCE CHARACTERISTICS

Typical INL, 2V Range, 25Mps



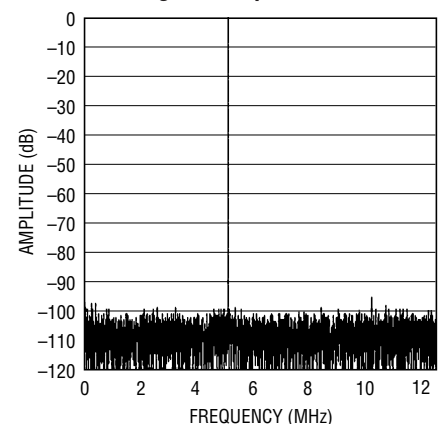
2226H G01

Typical DNL, 2V Range, 25Mps



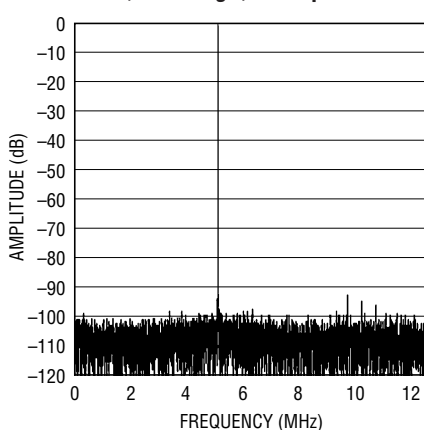
2226H G02

8192 Point FFT,  $f_{IN} = 5MHz$ ,  $-1dB$ , 2V Range, 25Mps



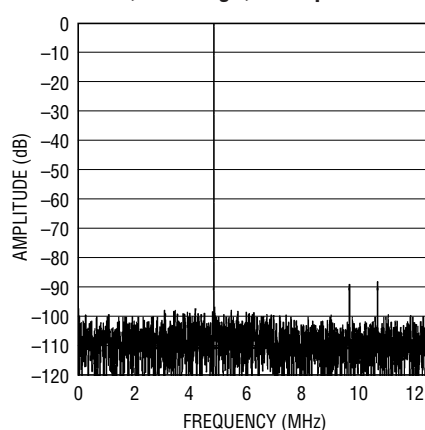
2226H G03

8192 Point FFT,  $f_{IN} = 30MHz$ ,  $-1dB$ , 2V Range, 25Mps



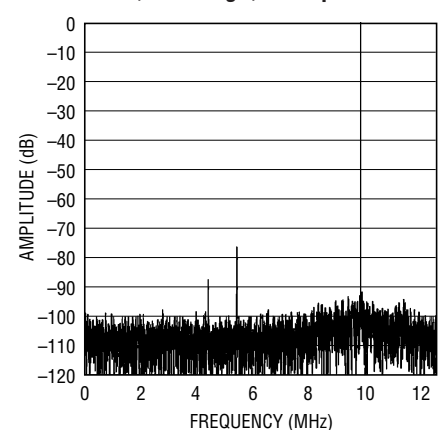
2226H G04

8192 Point FFT,  $f_{IN} = 70MHz$ ,  $-1dB$ , 2V Range, 25Mps



2226H G05

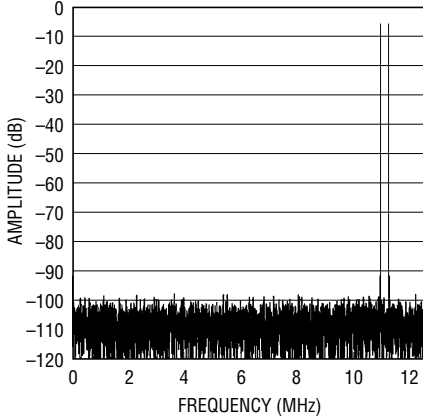
8192 Point FFT,  $f_{IN} = 140MHz$ ,  $-1dB$ , 2V Range, 25Mps



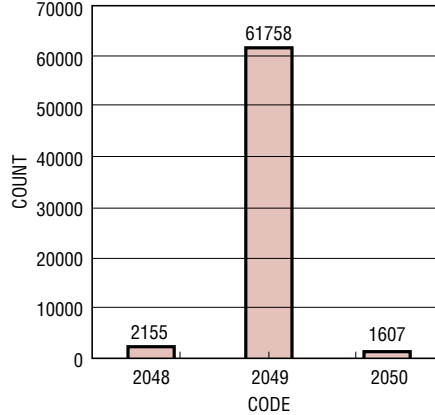
2226H G06

## TYPICAL PERFORMANCE CHARACTERISTICS

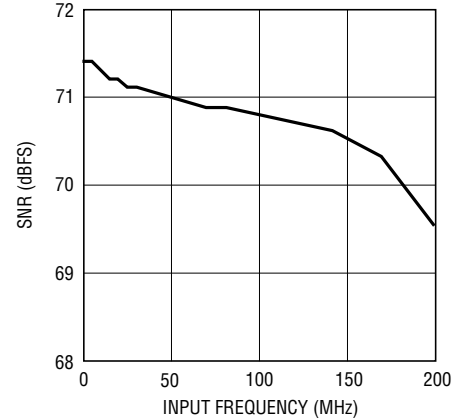
**8192 Point 2-Tone FFT,  
f<sub>IN</sub> = 10.9MHz and 13.8MHz,  
-1dB, 2V Range, 25Mpsps**



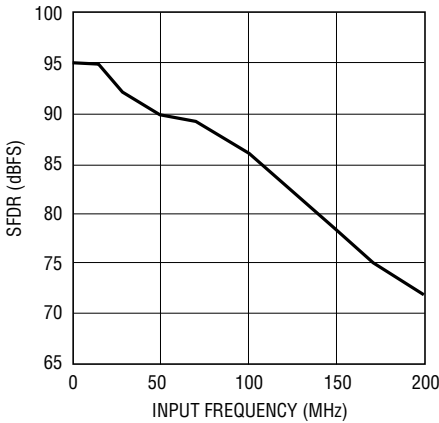
**Grounded Input Histogram,  
25Mpsps**



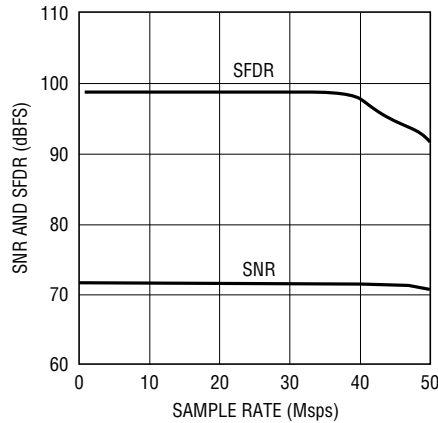
**SNR vs Input Frequency, -1dB,  
2V Range, 25Mpsps**



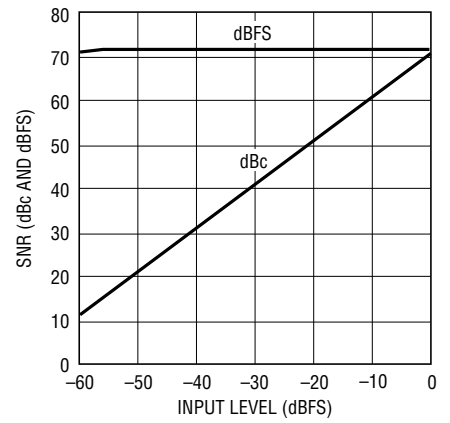
**SFDR vs Input Frequency, -1dB,  
2V Range, 25Mpsps**



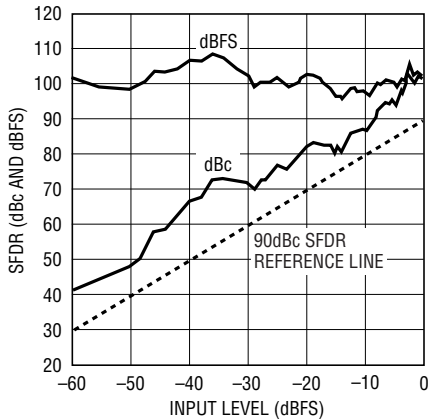
**SNR and SFDR vs Sample Rate,  
2V Range, f<sub>IN</sub> = 5MHz, -1dB**



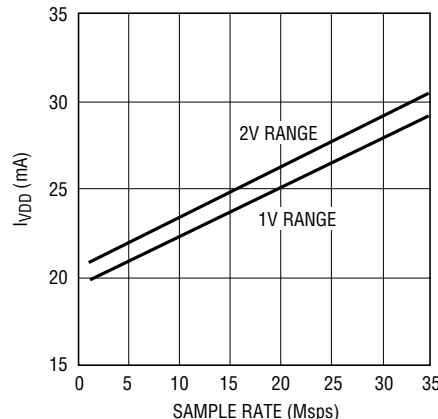
**SNR vs Input Level, f<sub>IN</sub> = 5MHz,  
2V Range, -1dB**



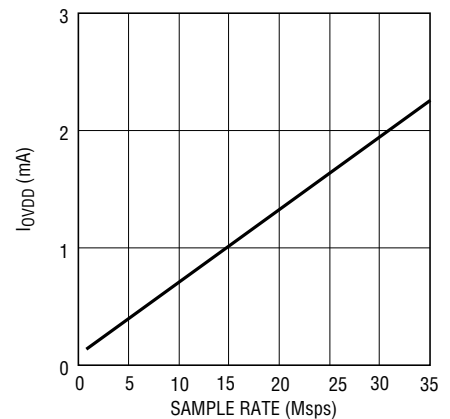
**SFDR vs Input Level, f<sub>IN</sub> = 5MHz,  
2V Range, 25Mpsps**



**I<sub>VDD</sub> vs Sample Rate, 5MHz Sine  
Wave Input, -1dB**



**I<sub>QVDD</sub> vs Sample Rate, 5MHz Sine  
Wave Input, -1dB, Q<sub>VDD</sub> = 1.8V**



## PIN FUNCTIONS

**GND (Pins 1, 4, 9, 13, 15, 18, 24, 25, 29, 32, 36, 37, 48):** ADC Power Ground.

**A<sub>IN+</sub> (Pin 2):** Positive Differential Analog Input.

**A<sub>IN-</sub> (Pin 3):** Negative Differential Analog Input.

**REFH (Pins 5, 6):** ADC High Reference. Bypass to Pins 7, 8 with a 0.1 $\mu$ F ceramic chip capacitor as close to the pin as possible. Also bypass to Pins 7, 8 with an additional 2.2 $\mu$ F ceramic chip capacitor and to GND with a 1 $\mu$ F ceramic chip capacitor.

**REFL (Pin 7, 8):** ADC Low Reference. Bypass to Pins 5, 6 with a 0.1 $\mu$ F ceramic chip capacitor as close to the pin as possible. Also bypass to Pin 5, 6 with an additional 2.2 $\mu$ F ceramic chip capacitor and to ground with a 1 $\mu$ F ceramic chip capacitor.

**V<sub>DD</sub> (Pins 10, 11, 12, 46, 47):** 3V Supply. Bypass to GND with 0.1 $\mu$ F ceramic chip capacitors.

**CLK (Pin 14):** Clock Input. The input sample starts on the positive edge.

**SHDN (Pin 16):** Shutdown Mode Selection Pin. Connecting SHDN to GND and  $\overline{OE}$  to GND results in normal operation with the outputs enabled. Connecting SHDN to GND and  $\overline{OE}$  to V<sub>DD</sub> results in normal operation with the outputs at high impedance. Connecting SHDN to V<sub>DD</sub> and  $\overline{OE}$  to GND results in nap mode with the outputs at high impedance. Connecting SHDN to V<sub>DD</sub> and  $\overline{OE}$  to V<sub>DD</sub> results in sleep mode with the outputs at high impedance.

If the clock duty cycle stabilizer is used, a >1 $\mu$ s high pulse should be applied to the SHDN pin once the power supplies are stable at power up.

**$\overline{OE}$  (Pin 17):** Output Enable Pin. Refer to SHDN pin function.

**NC (Pins 19, 20):** Do not connect these pins.

**D0–D11 (Pins 21–23, 26–28, 33–35, 38–40):** Digital Outputs. D11 is the MSB.

**OGND (Pin 30):** Output Driver Ground.

**OV<sub>DD</sub> (Pin 31):** Positive Supply for the Output Drivers. Bypass to ground with 0.1 $\mu$ F ceramic chip capacitor.

**OF (Pin 41):** Over/Under Flow Output. High when an over or under flow has occurred.

**MODE (Pin 42):** Output Format and Clock Duty Cycle Stabilizer Selection Pin. Connecting MODE to GND selects offset binary output format and turns the clock duty cycle stabilizer off. 1/3 V<sub>DD</sub> selects offset binary output format and turns the clock duty cycle stabilizer on. 2/3 V<sub>DD</sub> selects 2's complement output format and turns the clock duty cycle stabilizer on. V<sub>DD</sub> selects 2's complement output format and turns the clock duty cycle stabilizer off.

**SENSE (Pin 43):** Reference Programming Pin. Connecting SENSE to V<sub>CM</sub> selects the internal reference and a  $\pm 0.5$ V input range. V<sub>DD</sub> selects the internal reference and a  $\pm 1$ V input range. An external reference greater than 0.5V and less than 1V applied to SENSE selects an input range of  $\pm V_{SENSE}$ .  $\pm 1$ V is the largest valid input range.

**V<sub>CM</sub> (Pins 44, 45):** 1.5V Output and Input Common Mode Bias. Bypass to ground with 2.2 $\mu$ F ceramic chip capacitor.

# FUNCTIONAL BLOCK DIAGRAM

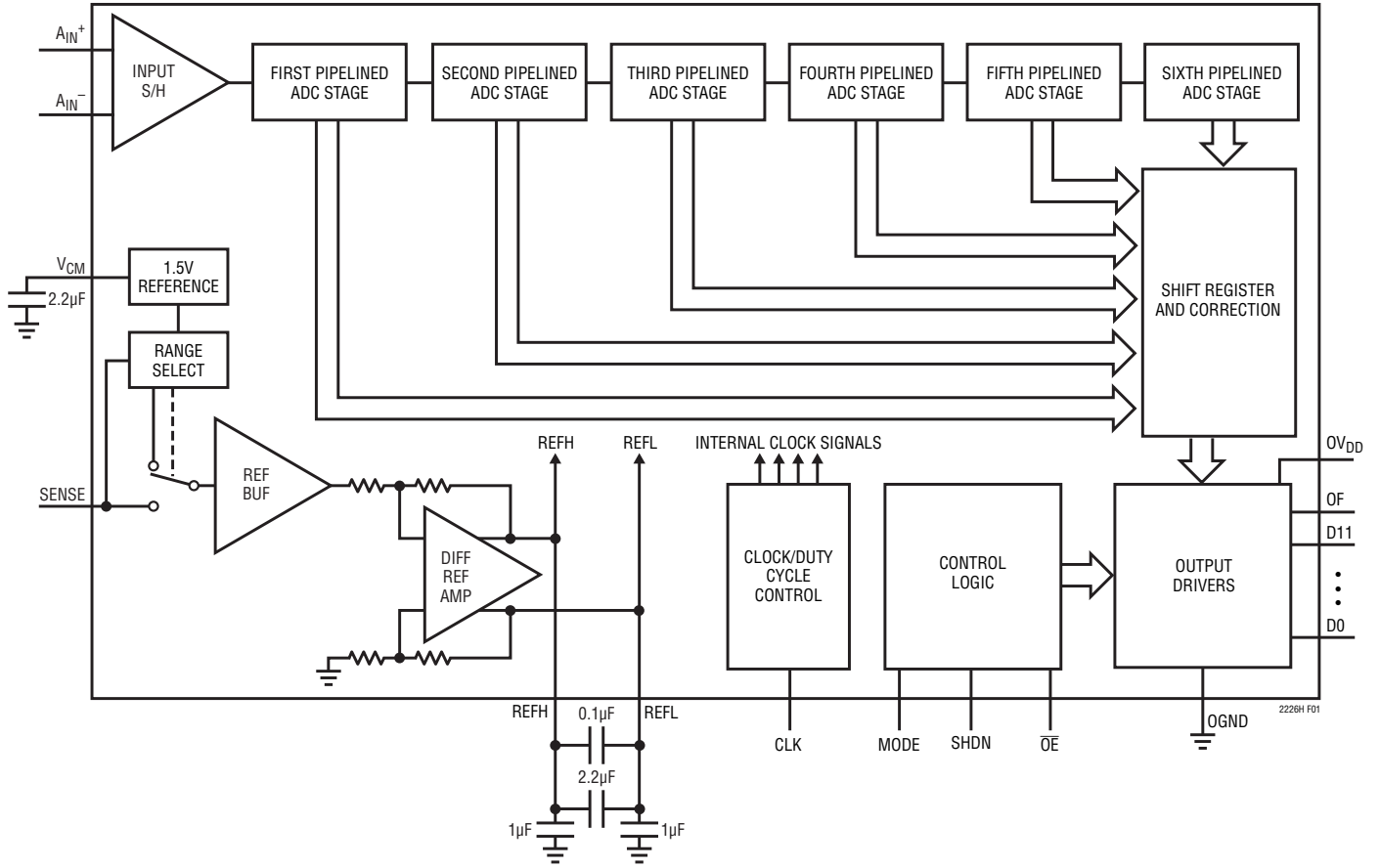
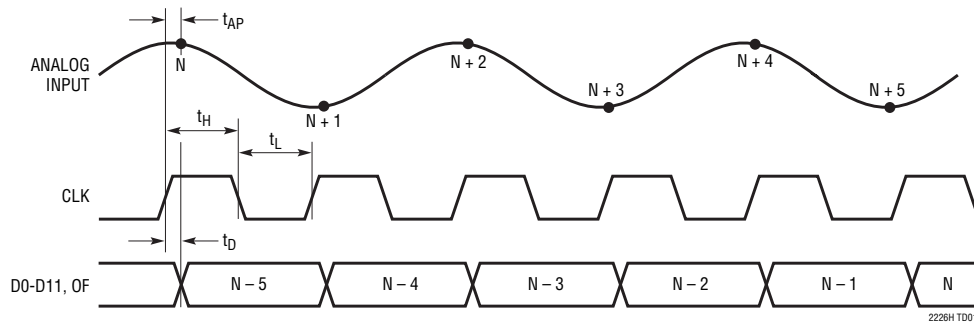


Figure 1. Functional Block Diagram

# TIMING DIAGRAM





## APPLICATIONS INFORMATION

### DYNAMIC PERFORMANCE

#### Signal-to-Noise Plus Distortion Ratio

The signal-to-noise plus distortion ratio [S/(N + D)] is the ratio between the RMS amplitude of the fundamental input frequency and the RMS amplitude of all other frequency components at the ADC output. The output is band limited to frequencies above DC to below half the sampling frequency.

#### Signal-to-Noise Ratio

The signal-to-noise ratio (SNR) is the ratio between the RMS amplitude of the fundamental input frequency and the RMS amplitude of all other frequency components except the first five harmonics and DC.

#### Total Harmonic Distortion

Total harmonic distortion is the ratio of the RMS sum of all harmonics of the input signal to the fundamental itself. The out-of-band harmonics alias into the frequency band between DC and half the sampling frequency. THD is expressed as:

$$\text{THD} = 20\text{Log}\left(\frac{\sqrt{V_2^2 + V_3^2 + V_4^2 + \dots + V_n^2}}{V_1}\right)$$

where V1 is the RMS amplitude of the fundamental frequency and V2 through Vn are the amplitudes of the second through nth harmonics. The THD calculated in this data sheet uses all the harmonics up to the fifth.

#### Intermodulation Distortion

If the ADC input signal consists of more than one spectral component, the ADC transfer function nonlinearity can produce intermodulation distortion (IMD) in addition to THD. IMD is the change in one sinusoidal input caused by the presence of another sinusoidal input at a different frequency.

If two pure sine waves of frequencies fa and fb are applied to the ADC input, nonlinearities in the ADC transfer function can create distortion products at the sum and difference frequencies of mfa ± nfb, where m and n = 0, 1, 2, 3, etc. The 3rd order intermodulation products are 2fa + fb, 2fb + fa, 2fa – fb and 2fb – fa. The intermodulation distortion

is defined as the ratio of the RMS value of either input tone to the RMS value of the largest 3rd order intermodulation product.

#### Spurious Free Dynamic Range (SFDR)

Spurious free dynamic range is the peak harmonic or spurious noise that is the largest spectral component excluding the input signal and DC. This value is expressed in decibels relative to the RMS value of a full scale input signal.

#### Input Bandwidth

The input bandwidth is that input frequency at which the amplitude of the reconstructed fundamental is reduced by 3dB for a full scale input signal.

#### Aperture Delay Time

The time from when CLK reaches mid-supply to the instant that the input signal is held by the sample and hold circuit.

#### Aperture Delay Jitter

The variation in the aperture delay time from conversion to conversion. This random variation will result in noise when sampling an AC input. The signal to noise ratio due to the jitter alone will be:

$$\text{SNR}_{\text{JITTER}} = -20\text{log}(2\pi \cdot f_{\text{IN}} \cdot t_{\text{JITTER}})$$

### CONVERTER OPERATION

As shown in Figure 1, the LTC2226H is a CMOS pipelined multistep converter. The converter has six pipelined ADC stages; a sampled analog input will result in a digitized value five cycles later (see the Timing Diagram section). For optimal AC performance the analog inputs should be driven differentially. For cost sensitive applications, the analog inputs can be driven single-ended with slightly worse harmonic distortion. The CLK input is single-ended. The LTC2226H has two phases of operation, determined by the state of the CLK input pin.

Each pipelined stage shown in Figure 1 contains an ADC, a reconstruction DAC and an interstage residue amplifier. In operation, the ADC quantizes the input to the stage and the quantized value is subtracted from the input by the

## APPLICATIONS INFORMATION

DAC to produce a residue. The residue is amplified and output by the residue amplifier. Successive stages operate out of phase so that when the odd stages are outputting their residue, the even stages are acquiring that residue and vice versa.

When CLK is low, the analog input is sampled differentially directly onto the input sample-and-hold capacitors, inside the “Input S/H” shown in the block diagram. At the instant that CLK transitions from low to high, the sampled input is held. While CLK is high, the held input voltage is buffered by the S/H amplifier which drives the first pipelined ADC stage. The first stage acquires the output of the S/H during this high phase of CLK. When CLK goes back low, the first stage produces its residue which is acquired by the second stage. At the same time, the input S/H goes back to acquiring the analog input. When CLK goes back high, the second stage produces its residue which is acquired by the third stage. An identical process is repeated for the third, fourth and fifth stages, resulting in a fifth stage residue that is sent to the sixth stage ADC for final evaluation.

Each ADC stage following the first has additional range to accommodate flash and amplifier offset errors. Results from all of the ADC stages are digitally synchronized such that the results can be properly combined in the correction logic before being sent to the output buffer.

### SAMPLE/HOLD OPERATION AND INPUT DRIVE

#### Sample/Hold Operation

Figure 2 shows an equivalent circuit for the LTC2226H CMOS differential sample-and-hold. The analog inputs are connected to the sampling capacitors ( $C_{\text{SAMPLE}}$ ) through NMOS transistors. The capacitors shown attached to each input ( $C_{\text{PARASITIC}}$ ) are the summation of all other capacitance associated with each input.

During the sample phase when CLK is low, the transistors connect the analog inputs to the sampling capacitors and they charge to and track the differential input voltage. When CLK transitions from low to high, the sampled input voltage is held on the sampling capacitors. During the hold phase when CLK is high, the sampling capacitors are disconnected from the input and the held voltage is passed to the ADC core for processing. As CLK transitions from high to low,

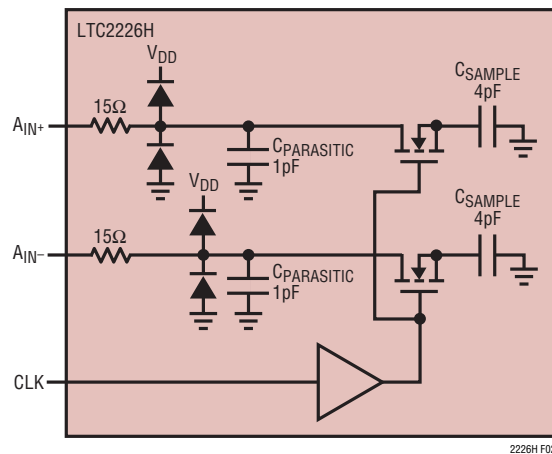


Figure 2. Equivalent Input Circuit

the inputs are reconnected to the sampling capacitors to acquire a new sample. Since the sampling capacitors still hold the previous sample, a charging glitch proportional to the change in voltage between samples will be seen at this time. If the change between the last sample and the new sample is small, the charging glitch seen at the input will be small. If the input change is large, such as the change seen with input frequencies near Nyquist, then a larger charging glitch will be seen.

#### Single-Ended Input

For cost sensitive applications, the analog inputs can be driven single-ended. With a single-ended input the harmonic distortion and INL will degrade, but the SNR and DNL will remain unchanged. For a single-ended input,  $A_{\text{IN}+}$  should be driven with the input signal and  $A_{\text{IN}-}$  should be connected to  $V_{\text{CM}}$  or a low noise reference voltage between 1V and 1.5V.

#### Common Mode Bias

For optimal performance the analog inputs should be driven differentially. Each input should swing  $\pm 0.5\text{V}$  for the 2V range or  $\pm 0.25\text{V}$  for the 1V range, around a common mode voltage of 1.5V. The  $V_{\text{CM}}$  output pin (Pins 44, 45) may be used to provide the common mode bias level.  $V_{\text{CM}}$  can be tied directly to the center tap of a transformer to set the DC input level or as a reference level to an op amp differential driver circuit. The  $V_{\text{CM}}$  pins must be bypassed to ground close to the ADC with a 2.2 $\mu\text{F}$  or greater capacitor.

## APPLICATIONS INFORMATION

### Input Drive Impedance

As with all high performance, high speed ADCs, the dynamic performance of the LTC2226H can be influenced by the input drive circuitry, particularly the second and third harmonics. Source impedance and reactance can influence SFDR. At the falling edge of CLK, the sample-and-hold circuit will connect the 4pF sampling capacitor to the input pin and start the sampling period. The sampling period ends when CLK rises, holding the sampled input on the sampling capacitor. Ideally the input circuitry should be fast enough to fully charge the sampling capacitor during the sampling period  $1/(2F_{\text{ENCODE}})$ ; however, this is not always possible and the incomplete settling may degrade the SFDR. The sampling glitch has been designed to be as linear as possible to minimize the effects of incomplete settling.

For the best performance, it is recommended to have a source impedance of  $100\Omega$  or less for each input. The source impedance should be matched for the differential inputs. Poor matching will result in higher even order harmonics, especially the second.

### Input Drive Circuits

Figure 3 shows the LTC2226H being driven by an RF transformer with a center tapped secondary. The secondary center tap is DC biased with  $V_{\text{CM}}$ , setting the ADC input signal at its optimum DC level. Terminating on the transformer secondary is desirable, as this provides a common mode path for charging glitches caused by the sample and

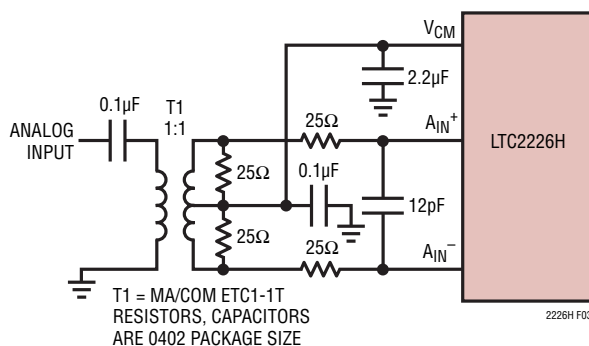


Figure 3. Single-Ended to Differential Conversion Using a Transformer

hold. Figure 3 shows a 1:1 turns ratio transformer. Other turns ratios can be used if the source impedance seen by the ADC does not exceed  $100\Omega$  for each ADC input. A disadvantage of using a transformer is the loss of low frequency response. Most small RF transformers have poor performance at frequencies below 1MHz.

Figure 4 demonstrates the use of a differential amplifier to convert a single ended input signal into a differential input signal. The advantage of this method is that it provides low frequency input response; however, the limited gain bandwidth of most op amps will limit the SFDR at high input frequencies.

Figure 5 shows a single-ended input circuit. The impedance seen by the analog inputs should be matched. This circuit is not recommended if low distortion is required.

The  $25\Omega$  resistors and 12pF capacitor on the analog inputs serve two purposes: isolating the drive circuitry from the sample-and-hold charging glitches and limiting the wideband noise at the converter input.

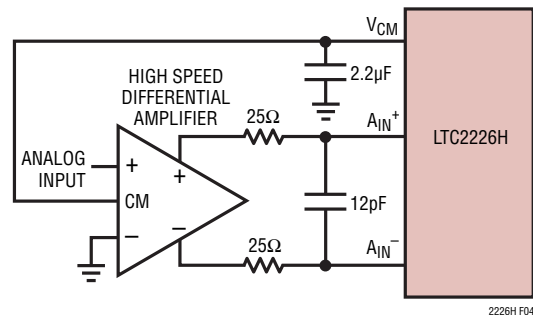


Figure 4. Differential Drive with an Amplifier

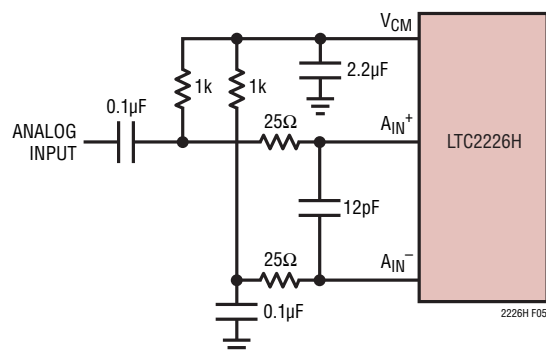


Figure 5. Single-Ended Drive

## APPLICATIONS INFORMATION

### Reference Operation

Figure 6 shows the LTC2226H reference circuitry consisting of a 1.5V bandgap reference, a difference amplifier and switching and control circuit. The internal voltage reference can be configured for two pin selectable input ranges of 2V ( $\pm 1V$  differential) or 1V ( $\pm 0.5V$  differential). Tying the SENSE pin to  $V_{DD}$  selects the 2V range; tying the SENSE pin to  $V_{CM}$  selects the 1V range.

The 1.5V bandgap reference serves two functions: its output provides a DC bias point for setting the common mode voltage of any external input circuitry; additionally, the reference is used with a difference amplifier to generate the differential reference levels needed by the internal ADC circuitry. An external bypass capacitor is required for the 1.5V reference output,  $V_{CM}$ . This provides a high frequency low impedance path to ground for internal and external circuitry.

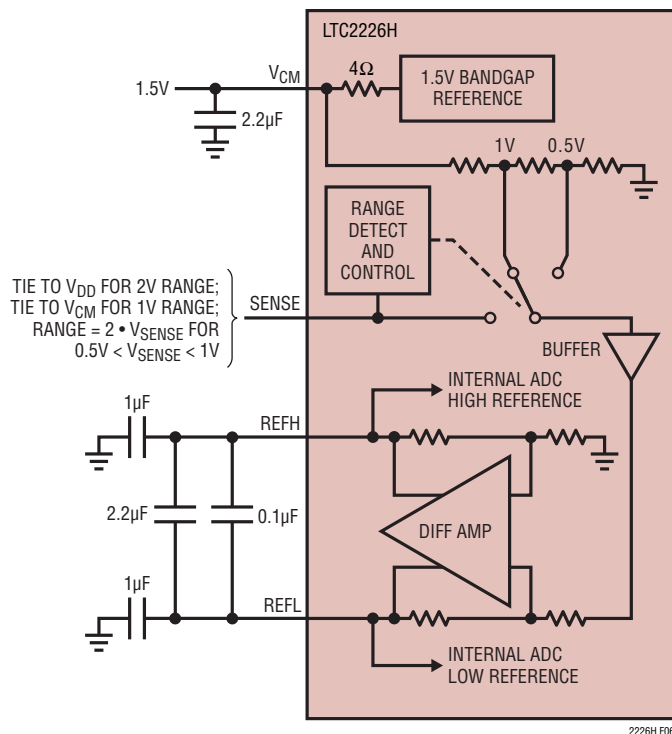


Figure 6. Equivalent Reference Circuit

The difference amplifier generates the high and low reference for the ADC. High speed switching circuits are connected to these outputs and they must be externally bypassed.

Other voltage ranges in-between the pin selectable ranges can be programmed with two external resistors as shown in Figure 7. An external reference can be used by applying its output directly or through a resistor divider to SENSE. It is not recommended to drive the SENSE pin with a logic device. The SENSE pin should be tied to the appropriate level as close to the converter as possible. If the SENSE pin is driven externally, it should be bypassed to ground as close to the device as possible with a 1μF ceramic capacitor.

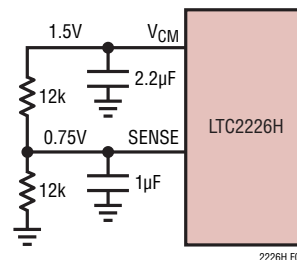
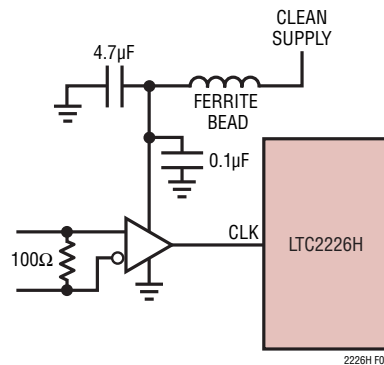


Figure 7. 1.5V Range ADC



IF LVDS USE FIN1002 OR FIN1018.  
FOR PECL, USE AZ1000ELT21 OR SIMILAR

Figure 8. CLK Drive Using an LVDS or PECL to CMOS Converter

## APPLICATIONS INFORMATION

### Input Range

The input range can be set based on the application. The 2V input range will provide the best signal-to-noise performance while maintaining excellent SFDR. The 1V input range will have better SFDR performance, but the SNR will degrade by 3.8dB.

### Driving the Clock Input

The CLK input can be driven directly with a CMOS or TTL level signal. A differential clock can also be used along with a low-jitter CMOS converter before the CLK pin (see Figure 8).

The noise performance of the LTC2226H can depend on the clock signal quality as much as on the analog input. Any noise present on the clock signal will result in additional aperture jitter that will be RMS summed with the inherent ADC aperture jitter.

### Maximum and Minimum Conversion Rates

The maximum conversion rate for the LTC2226H is 25Msps. For the ADC to operate properly, the CLK signal should have a 50% ( $\pm 5\%$ ) duty cycle. Each half cycle must have at least 18.9ns for the ADC internal circuitry to have enough settling time for proper operation.

An optional clock duty cycle stabilizer circuit can be used if the input clock has a non 50% duty cycle. This circuit uses the rising edge of the CLK pin to sample the analog input. The falling edge of CLK is ignored and the internal falling edge is generated by a phase-locked loop. The input clock duty cycle can vary and the clock duty cycle stabilizer will maintain a constant 50% internal duty cycle. If the clock is turned off for a long period of time, the duty cycle stabilizer circuit will require a hundred clock cycles for the PLL to lock onto the input clock. To use the clock duty cycle stabilizer, the MODE pin should be connected to  $1/3V_{DD}$  or  $2/3V_{DD}$  using external resistors.

If the clock duty cycle stabilizer is used, a  $>1\mu\text{s}$  high pulse should be applied to the SHDN pin once the power supplies are stable at power up.

The lower limit of the LTC2226H sample rate is determined by droop of the sample-and-hold circuits. The pipelined architecture of this ADC relies on storing analog signals on small valued capacitors. Junction leakage will discharge the capacitors. The specified minimum operating frequency for the LTC2226H is 1Msps.

## DIGITAL OUTPUTS

Table 1 shows the relationship between the analog input voltage, the digital data bits, and the overflow bit.

### Digital Output Buffers

Table 1. Output Codes vs Input Voltage

$A_{IN}^+ - A_{IN}^-$ (2V Range)	OF	D11 – D0 (Offset Binary)	D11 – D0 (2's Complement)
$>+1.000000\text{V}$	1	11 11 1111 1111	0111 1111 1111
$+0.999512\text{V}$	0	11 11 1111 1111	0111 1111 1111
$+0.999024\text{V}$	0	11 11 1111 1110	0111 1111 1110
$+0.000488\text{V}$	0	10 00 0000 0001	00 00 0000 0001
$0.000000\text{V}$	0	10 00 0000 0000	00 00 0000 0000
$-0.000488\text{V}$	0	01 11 1111 1111	11 11 1111 1111
$-0.000976\text{V}$	0	01 11 1111 1110	11 11 1111 1110
$-0.999512\text{V}$	0	0000 0000 0001	1000 0000 0001
$-1.000000\text{V}$	0	0000 0000 0000	1000 0000 0000
$<-1.000000\text{V}$	1	0000 0000 0000	1000 0000 0000

Figure 9 shows an equivalent circuit for a single output buffer. Each buffer is powered by  $OV_{DD}$  and OGND, isolated from the ADC power and ground. The additional

N-channel transistor in the output driver allows operation down to low voltages. The internal resistor in series with the output makes the output appear as  $50\Omega$  to external circuitry and may eliminate the need for external damping resistors.

## APPLICATIONS INFORMATION

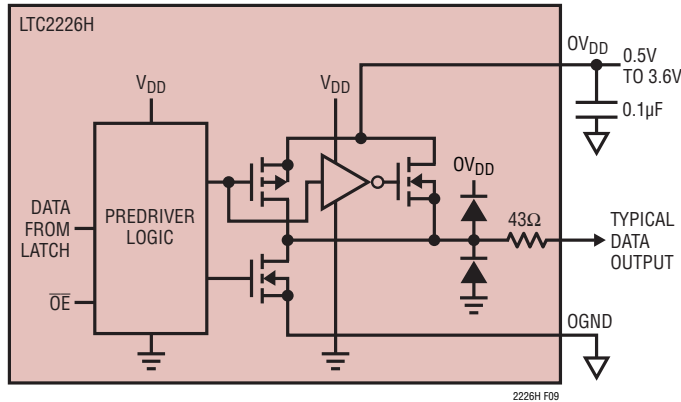


Figure 9. Digital Output Buffer

As with all high speed/high resolution converters, the digital output loading can affect the performance. The digital outputs of the LTC2226H should drive a minimal capacitive load to avoid possible interaction between the digital outputs and sensitive input circuitry. The output should be buffered with a device such as an ALVCH16373 CMOS latch. For full speed operation the capacitive load should be kept under 10pF.

Lower  $OV_{DD}$  voltages will also help reduce interference from the digital outputs.

### Data Format

Using the MODE pin, the LTC2226H parallel digital output can be selected for offset binary or 2's complement format. Connecting MODE to GND or  $1/3V_{DD}$  selects offset binary output format. Connecting MODE to  $2/3V_{DD}$  or  $V_{DD}$  selects 2's complement output format.

An external resistor divider can be used to set the  $1/3V_{DD}$  or  $2/3V_{DD}$  logic values. Table 2 shows the logic states for the MODE pin.

Table 2. MODE Pin Function

MODE PIN	OUTPUT FORMAT	CLOCK DUTY CYCLE STABILIZER
0	Offset Binary	Off
$1/3V_{DD}$	Offset Binary	On
$2/3V_{DD}$	2's Complement	On
$V_{DD}$	2's Complement	Off

### Overflow Bit

When OF outputs a logic high the converter is either over-ranged or underranged.

### Output Driver Power

Separate output power and ground pins allow the output drivers to be isolated from the analog circuitry. The power supply for the digital output buffers,  $OV_{DD}$ , should be tied to the same power supply as for the logic being driven. For example if the converter is driving a DSP powered by a 1.8V supply, then  $OV_{DD}$  should be tied to that same 1.8V supply.

## APPLICATIONS INFORMATION

$OV_{DD}$  can be powered with any voltage from 500mV up to 3.6V.  $OGND$  can be powered with any voltage from GND up to 1V and must be less than  $OV_{DD}$ . The logic outputs will swing between  $OGND$  and  $OV_{DD}$ .

### Output Enable

The outputs may be disabled with the output enable pin,  $\overline{OE}$ .  $\overline{OE}$  high disables all data outputs including OF.

### Sleep and Nap Modes

The converter may be placed in shutdown or nap modes to conserve power. Connecting SHDN to GND results in normal operation. Connecting SHDN to  $V_{DD}$  and  $\overline{OE}$  to  $V_{DD}$  results in sleep mode, which powers down all circuitry including the reference and typically dissipates 1mW. When exiting sleep mode it will take milliseconds for the output data to become valid because the reference capacitors have to recharge and stabilize. Connecting SHDN to  $V_{DD}$  and  $\overline{OE}$  to GND results in nap mode, which typically dissipates 15mW. In nap mode, the on-chip reference circuit is kept on, so that recovery from nap mode is faster than that from sleep mode, typically taking 100 clock cycles. In both sleep and nap modes, all digital outputs are disabled and enter the Hi-Z state.

### Grounding and Bypassing

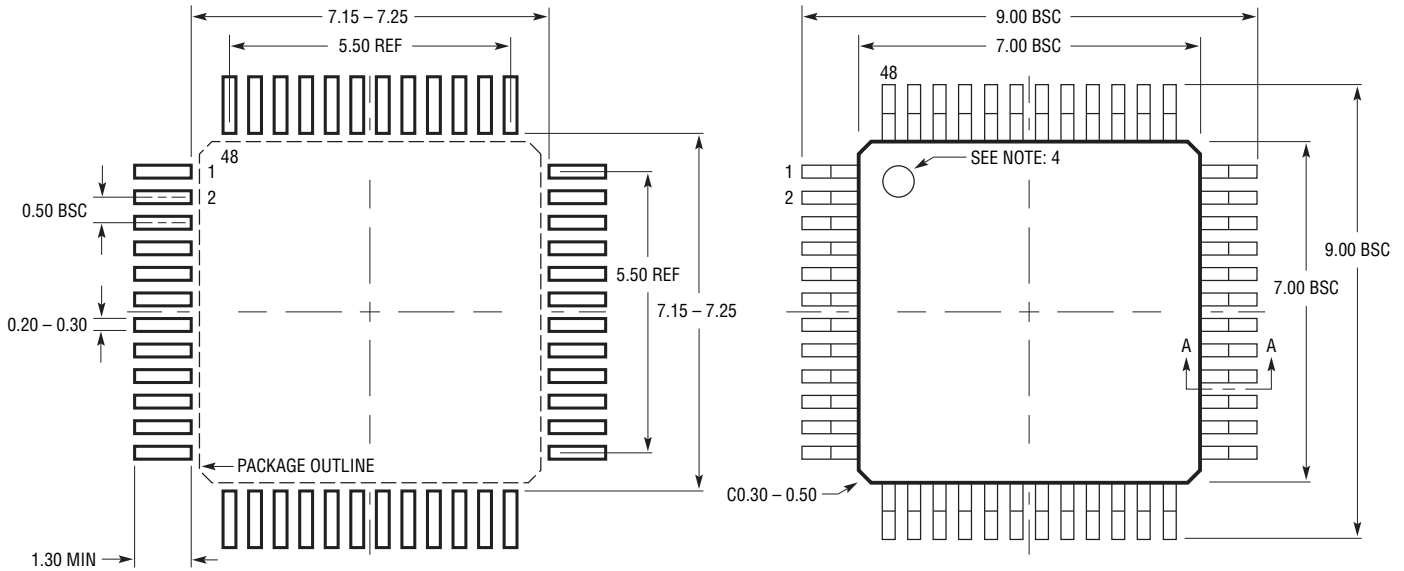
The LTC2226H requires a printed circuit board with a clean, unbroken ground plane. A multilayer board with an internal ground plane is recommended. Layout for the printed circuit board should ensure that digital and analog signal lines are separated as much as possible. In particular, care should be taken not to run any digital track alongside an analog signal track or underneath the ADC.

High quality ceramic bypass capacitors should be used at the  $V_{DD}$ ,  $OV_{DD}$ ,  $V_{CM}$ , REFH, and REFL pins. Bypass capacitors must be located as close to the pins as possible. Of particular importance is the 0.1 $\mu$ F capacitor between REFH and REFL. This capacitor should be placed as close to the device as possible (1.5mm or less). A size 0402 ceramic capacitor is recommended. The large 2.2 $\mu$ F capacitor between REFH and REFL can be somewhat further away. The traces connecting the pins and bypass capacitors must be kept short and should be made as wide as possible.

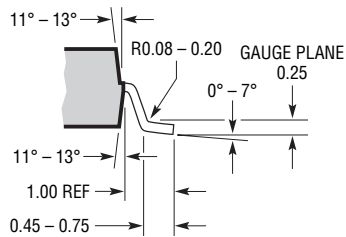
The LTC2226H differential inputs should run parallel and close to each other. The input traces should be as short as possible to minimize capacitance and to minimize noise pickup.

## PACKAGE DESCRIPTION

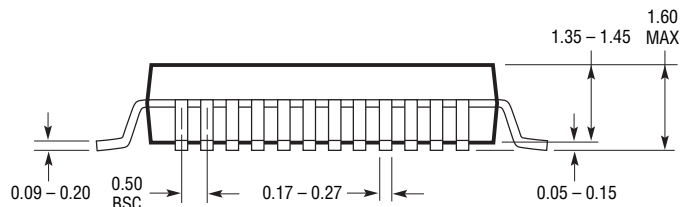
### LX Package 48-Lead Plastic LQFP (7mm × 7mm) (Reference LTC DWG # 05-08-1760 Rev 0)



RECOMMENDED SOLDER PAD LAYOUT  
APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED



SECTION A - A



LX48 LQFP 0907 REV D

**NOTE:**

1. PACKAGE DIMENSIONS CONFORM TO JEDEC #MS-026 PACKAGE OUTLINE
2. DIMENSIONS ARE IN MILLIMETERS
3. DIMENSIONS OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.25mm ON ANY SIDE, IF PRESENT

4. PIN-1 INDENTIFIER IS A MOLDED INDENTATION, 0.50mm DIAMETER
5. DRAWING IS NOT TO SCALE



**REVISION HISTORY** (Revision history begins at Rev C)

REV	DATE	DESCRIPTION	PAGE NUMBER
C	01/11	Removed Tape and Reel information from Order Information section	2